

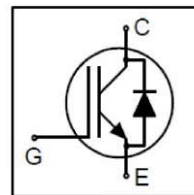
Product Summary	
V_{CES}	600V
I_C	15A
$V_{CE(sat),typ}$	1.5V ($T_J = 25^\circ\text{C}$)
Package	DTGP15N60: TO-220 DTGF15N60: TO-220F DTGK15N60: TO-263

Features

- Low $V_{CE(sat)}$
- Fast Switching
- High Ruggedness
- Short-circuit Rated

Applications

- Home Appliances
- Compressors / Air Conditioning
- Motor Control
- General Purpose Inverters



Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Collector-to-Emitter Voltage	V_{CES}	600	V
Gate-to-Emitter Voltage	V_{GES}	± 20	
DC Collector Current ($T_c = 100^\circ\text{C}$, limited by max T_J)	TO-220, TO-263	18.5	A
	TO-220F	10	
Pulsed Collector Current (pulse width limited by max T_J)	I_{CM}	60	
Diode Forward Current ($T_c = 100^\circ\text{C}$, limited by max T_J)	TO-220, TO-263	20	A
	TO-220F	10	
Diode Pulsed Current (pulse width limited by max T_J)	I_{FM}	60	
Maximum Power Dissipation ($T_c = 25^\circ\text{C}$, $T_J = 150^\circ\text{C}$)	TO-220, TO-263	114	W
	TO-220F	45	
Operating Junction Temperature	T_J	-40 to +150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to +150	

Static Electrical Characteristics ⁽¹⁾

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector-to-Emitter Breakdown Voltage	BV_{CES}	$V_{GE} = 0V, I_C = 250\mu A$	600	-	-	V
Collector-to-Emitter Leakage Current	I_{CES}	$V_{CE} = 600V, V_{GE} = 0V$	-	-	10	μA
		$V_{CE} = 600V, V_{GE} = 0V$ $T_J = 125^\circ C$	-	-	250	
Gate-to-Emitter Leakage Current	I_{GES}	$V_{CE} = 0V, V_{GE} = \pm 20V$	-	-	100	nA
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 250\mu A$	5.0	6.0	7.0	V
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 15A$	-	1.5	1.9	V
		$V_{GE} = 15V, I_C = 15A,$ $T_J = 125^\circ C$	-	1.8	-	
Diode Forward Voltage	V_F	$V_{GE} = 0V, I_F = 15A$	-	1.6	2.1	V
		$V_{GE} = 0V, I_F = 15A$ $T_J = 125^\circ C$	-	1.4	-	

Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Junction-to-Ambient Thermal Resistance (TO-220, TO-263)	$R_{\theta JA}$	-	-	62	$^\circ C/W$
Junction-to-Case Thermal Resistance (TO-220, TO-263), IGBT	$R_{\theta JC}$	-	-	1.1	
Junction-to-Case Thermal Resistance (TO-220, TO-263), Diode		-	-	1.4	
Junction-to-Ambient Thermal Resistance (TO-220F)	$R_{\theta JA}$	-	-	65	
Junction-to-Case Thermal Resistance (TO-220F), IGBT	$R_{\theta JC}$	-	-	2.8	
Junction-to-Case Thermal Resistance (TO-220F), Diode		-	-	3.5	

Dynamic Electrical Characteristics ⁽¹⁾

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_G	$V_{CC} = 400V,$ $V_{GE} = 15V,$ $I_C = 15A$	-	45	-	nC
Input Capacitance	C_{iss}	$V_{CE} = 30V,$ $V_{GE} = 0V,$ $f = 1MHz$	-	930	-	pF
Output Capacitance	C_{oss}		-	85	-	
Reverse Transfer Capacitance	C_{rss}		-	16	-	

Switching Characteristics, Inductive Load ^{(1), (2)}

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(ON)}$	$V_{CC} = 400V,$ $V_{GE} = 0/15V,$ $R_G = 10\Omega,$ $I_C = 15A,$ $L_{load} = 3mH$ (Energy losses include "tail" and diode reverse recovery)	-	24	-	ns
Rise Time	t_r		-	19	-	
Turn-off delay time	$t_{d(OFF)}$		-	89	-	
Fall Time	t_f		-	70	-	
Turn-On Switching Loss	E_{on}		-	0.28	-	mJ
Turn-Off Switching Loss	E_{off}		-	0.28	-	
Total Switching Loss	E_{ts}		-	0.56	-	
Diode Reverse Recovery Time	t_{rr}		-	46	-	ns
Short Circuit Capability	t_{SC}	$V_{GE} = 15V, T_C = 25^\circ C$	5	10	-	μs
Short Circuit Collector Current	$I_{C(SC)}$	$V_{CC} \leq 400V, V_P \leq 600V$	-	60	-	A

(1) $T_J = 25^\circ C$ unless otherwise specified.

(2) t_r : from 10% of I_C to 90% of I_C ; t_f : from 90% of I_C to 10% of I_C ;

E_{on} : from 10% of V_{GE} to 10% of V_{CE} ; E_{off} : from 90% of V_{GE} to 10% of I_C .

Typical Electrical Characteristics

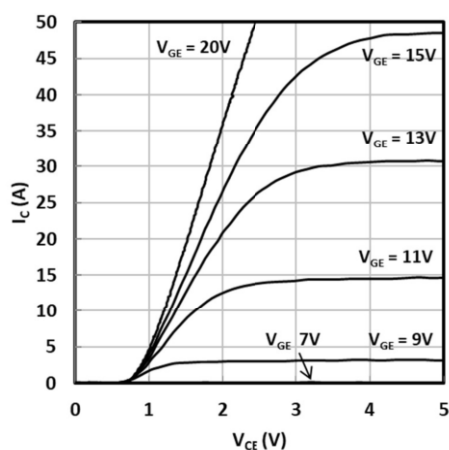


Fig. 1 Typical output characteristics

($T_J = 25\text{ }^\circ\text{C}$, $t_p = 250\text{ }\mu\text{s}$)

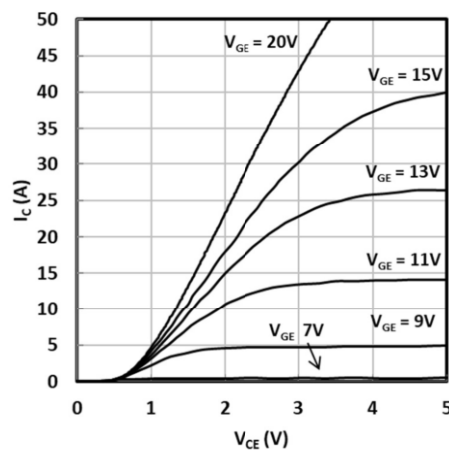


Fig. 2 Typical output characteristics

($T_J = 150\text{ }^\circ\text{C}$, $t_p = 250\text{ }\mu\text{s}$)

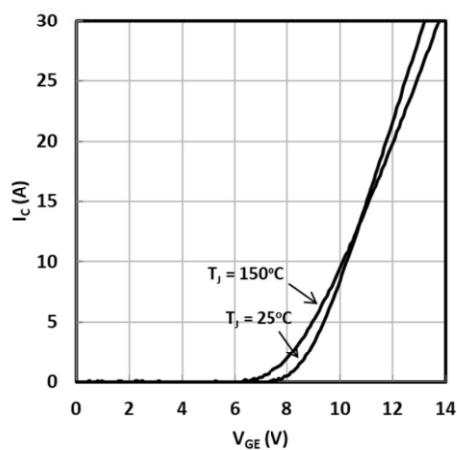


Fig. 3 Typical transfer characteristics

($V_{CE} = 20\text{ V}$, $t_p = 250\text{ }\mu\text{s}$)

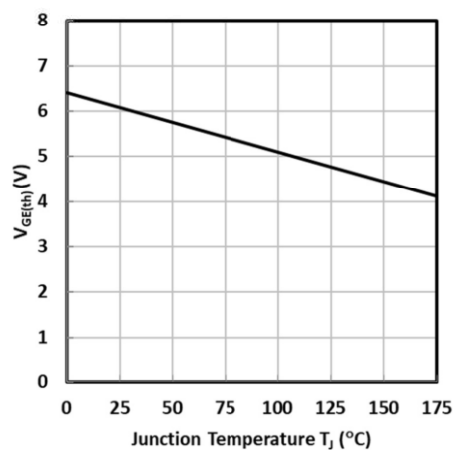


Fig. 4 Typical gate threshold voltage as a function of junction temperature

($V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$)

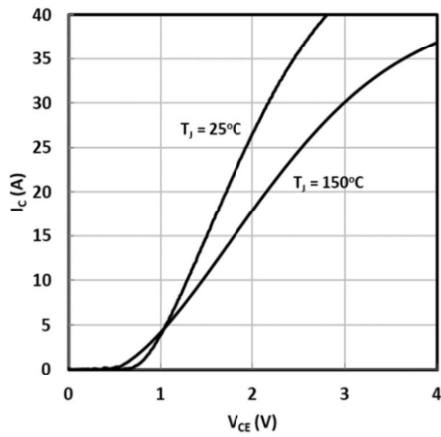


Fig. 5 Typical saturation voltage characteristics
($V_{GE} = 15\text{ V}$, $t_p = 250\ \mu\text{s}$)

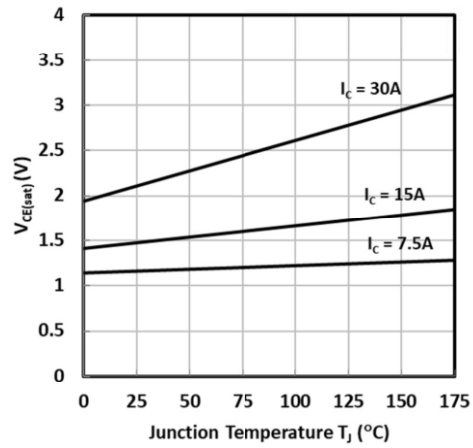


Fig. 6 Typical saturation voltage as a function of junction temperature
($V_{GE} = 15\text{ V}$, $t_p = 250\ \mu\text{s}$)

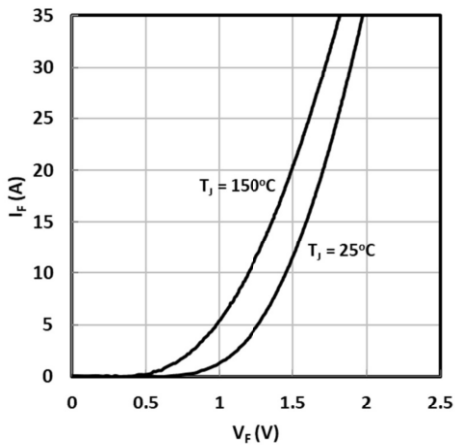


Fig. 7 Typical diode forward current as a function of forward voltage
($V_{GE} = 0\text{ V}$, $t_p = 250\ \mu\text{s}$)

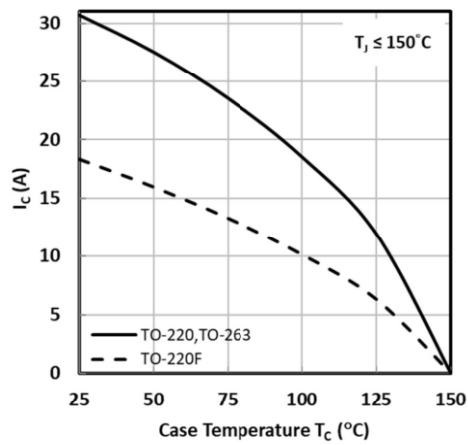


Fig. 8 Maximum DC collector current as a function of case temperature

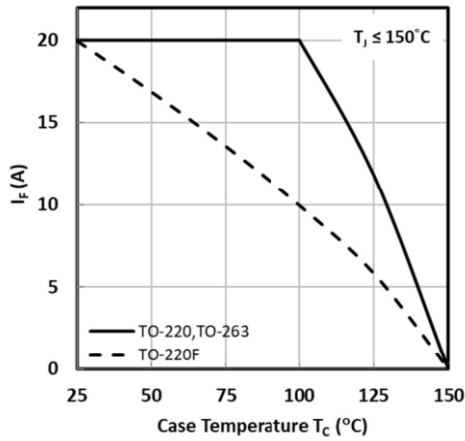


Fig. 9 Maximum DC diode forward current as a function of case temperature
(I_F limited by bonding wire)

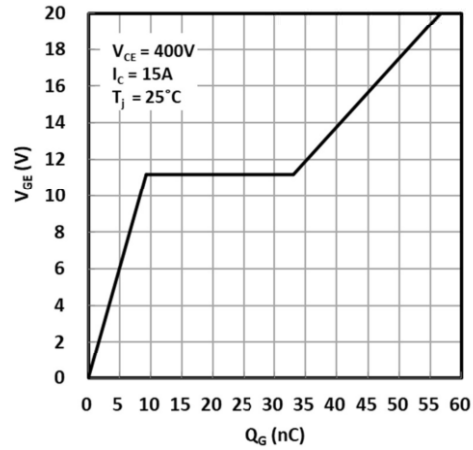


Fig. 10 Typical gate charge characteristics

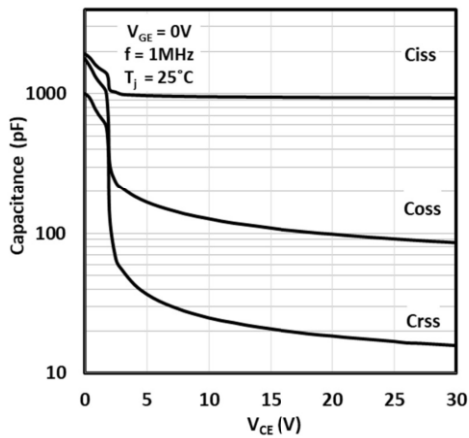
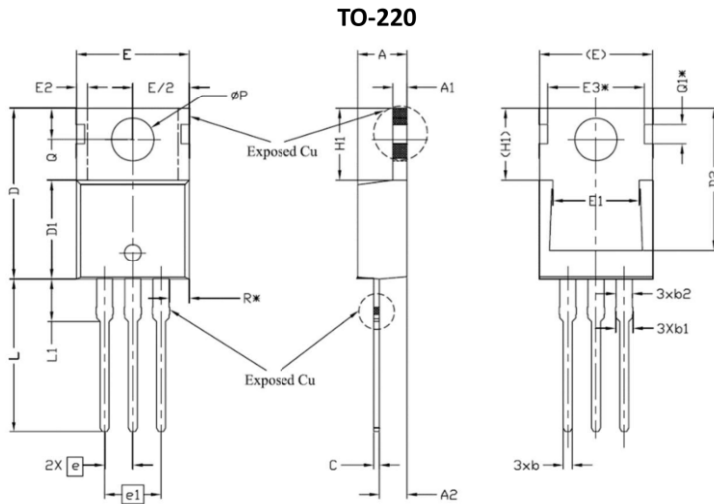
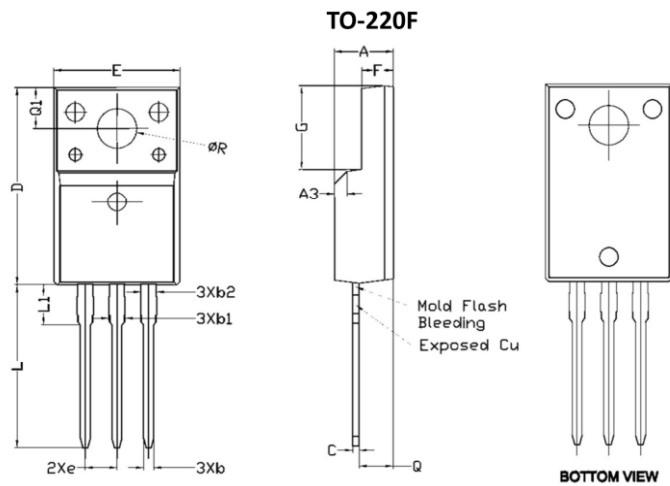


Fig. 11 Typical capacitance as a function of collector-to-emitter voltage

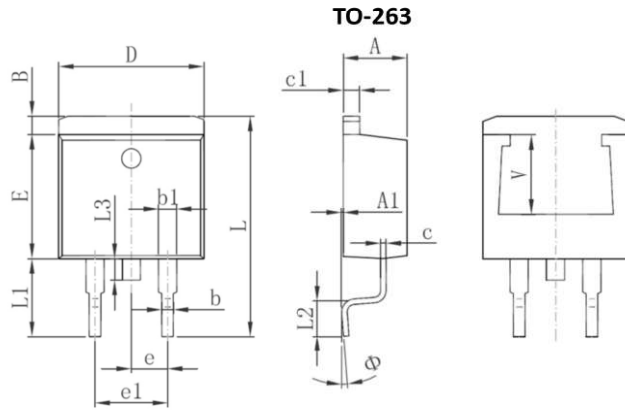
Package Drawing



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	1.15	1.27	1.40
A2	2.30	2.48	2.70
b	0.70	0.80	0.90
b1	1.20	1.55	1.75
b2	1.20	1.45	1.70
c	0.40	0.50	0.60
D	14.70	15.37	16.00
D1	8.82	8.92	9.02
D2	12.63	12.73	12.83
E	9.96	10.16	10.36
E1	6.86	7.77	8.89
E2	-	-	0.76
E3*	8.70REF.		
e	2.54BSC		
e1	5.08BSC		
H1	6.30	6.45	6.60
L	13.47	13.72	13.97
L1	3.60	3.80	4.00
ϕP	3.75	3.84	3.93
Q	2.60	2.80	3.00
Q1*	1.73REF.		
R*	1.82REF.		



SYMBOL	DIMENSIONS		
	Min.	Nom.	Max.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
C	0.45	0.50	0.63
D	15.80	15.87	15.97
e	2.54		
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ϕR	3.08	3.18	3.28



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	4.470	4.670
A1	0.000	0.150
B	1.120	1.420
b	0.710	0.910
b1	1.170	1.370
c	0.310	0.530
c1	1.170	1.370
D	10.010	10.310
E	8.500	8.900
e	2.540 TYP.	
e1	4.980	5.180
L	14.940	15.500
L1	4.950	5.450
L2	2.340	2.740
L3	1.300	1.700
φ	0°	8°
V	5.600 REF.	

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Din-Tek Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Din-Tek"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Din-Tek makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Din-Tek disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Din-Tek's knowledge of typical requirements that are often placed on Din-Tek products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Din-Tek's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Din-Tek products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Din-Tek product could result in personal injury or death. Customers using or selling Din-Tek products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Din-Tek personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Din-Tek. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Din-Tek Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Din-Tek documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Din-Tek Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Din-Tek documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.